

Product Description

Shin-Etsu's KE-4828 is a UL 94 HB rated, single component, room-temperature cure, thixotropic adhesive that will cure to form a tough, durable elastomer. KE-4828 is a low odor, neutral cure, non-corrosive product that exhibits excellent, unprimed adhesion to metals, plastics, glass, and ceramics.

Product Features

- UL 94 HB certified
- Single component
- Room-temperature cure
- Thixotropic paste
- Low odor and non-corrosive

Typical Applications

- Solar panel sealing
- Form-in-place gasketing
- Sealing electronics

Typical Properties

Type	Adhesive/Sealant
Cure Type	Condensation
One/Two Component	One
UL Listing	Y
Color	Black, White
Density @ 23C (g/cm ³)	1.40
Cure Conditions	7days @ 23C/50% RH
Tack Free Time (min)	6
Shore A Hardness	35
Tensile Strength (MPa)	1.60
% Elongation	350
Shear Strength (MPa)	1.00
Volume Resistivity (TΩ·m)	1.1
Dielectric Strength (kV/mm)	27
Usable Temperature Range (C)	-40 to +180

Note: Values are not for specification purposes.

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